

Networks Code Information(1/2)

S 5 X X X X X X X X - X X X X
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15

1. System LSI (S)

2. Large Classification : MOS (5)

3. Small Classification

- A : Audio
- B : Analog Core
- C : Camera
- D : Display
- F : CCD
- G : General
- H : Home(Appliance) Video
- I : Digital Core
- K : CIS
- L : Optical
- M : Mobile Automation
- N : Network
- S : SLINK(Serial Link)
- T : Telecom
- V : Process Vehicle
- W : Library
- X : MODULE(CAMERA MODULE)
- Y : Memory Card
- Z : Custom
- 2 : EEPROM
- 4 : DRAM CORE
- 6 : FLASH CORE

4~7.

Serial No

8. Version

A~Z

*1st Version → X

9~10. Mask Option

11. " - "

12. Package Type

- | | |
|-----------|--------------|
| 1 : TEBGA | 2 : MODULE |
| 3 : QFN | 4 : MLF |
| 5 : ELP2 | 6 : WFP |
| 7 : LPCC | 8 : FCBGA |
| 9 : PBGA | A : SDIP |
| B : BGA | C : CHIP BIZ |
| D : DIP | E : LQFP |
| F : BCC++ | G : ELQFP |
| H : ULGA | J : ELP |
| K : SBGA | M : QFPH |
| P : PLCC | Q : QFP |
| R : TSSOP | S : SOP |
| T : TQFP | U : UELP |
| V : SSOP | W : WAFER |
| X : ETQFP | Y : FBGA |
| Z : STBGA | |

13. Reserved

- | | |
|------------------|------------------|
| 0 : none | 1 : PKG Option 1 |
| 2 : PKG Option 2 | 3 : PKG Option 3 |
| | |
| G : PKG Option G | H : PKG Option H |

14. Packing

- | | |
|------------------------------------|-----------------|
| B : Tube | U : Bulk |
| R : Tray | T : Tape & Reel |
| S : Tape & Reel Reverse | C : Chip Biz |
| D : Chip Biz (3 Inch tray) | |
| E : Chip Biz (4 Inch tray) | |
| F : Chip Biz (Reverse) | |
| W : WF Biz Draft Wafer | |
| X : WF Biz Full Cutting | |
| 3 : Tape & Reel (Halogen-Free PKG) | |
| 4 : Tray (Halogen-Free PKG) | |
| 5 : Tube (Halogen-Free PKG) | |
| 7 : Tape & Reel (Lead-Free PKG) | |
| 8 : Tray (Lead-Free PKG) | |
| 9 : Tube (Lead-Free PKG) | |

Networks Code Information(2/2)

<u>S</u>	<u>5</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	-	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15

15. Customer

- 0 : None
- 1 : Bonding Option 1
- 2 : Bonding Option 2
- 3 : Bonding Option 3
- 4 : Bonding Option 4
- 5 : Bonding Option 5
- 6 : Bonding Option 6
- 7 : Bonding Option 7
- 8 : Bonding Option 8
- 9 : Bonding Option 9
- A : Special Marking 1
- B : Special Marking 2
- C : Special Marking 3
- D : Special Marking 4
- E : Special Marking 5
- F : Special Marking 6
- K : Reliability Test
- L : No Logo
- M : No Marking
- N : ANAM Assembly
- Q : Bonding Option 10
- R : Bonding Option 11
- S : Bonding Option 12
- T : Bonding Option 13
- U : Bonding Option 14
- Z : Customer Option

